كلية الهندسة
جامعة المنصورة

Smart Temprature Control System

This is an embedded system desiged based on Pic16f877A famous microcontrollers inteoduced from microchip and simply adjust the temprature of the system .

TEMPRATURE CONTROL

V1

Supervised By :

DR. MOHAMMED MOAWED

Texas Instruments

Microchip

TEAM MEMBERS :

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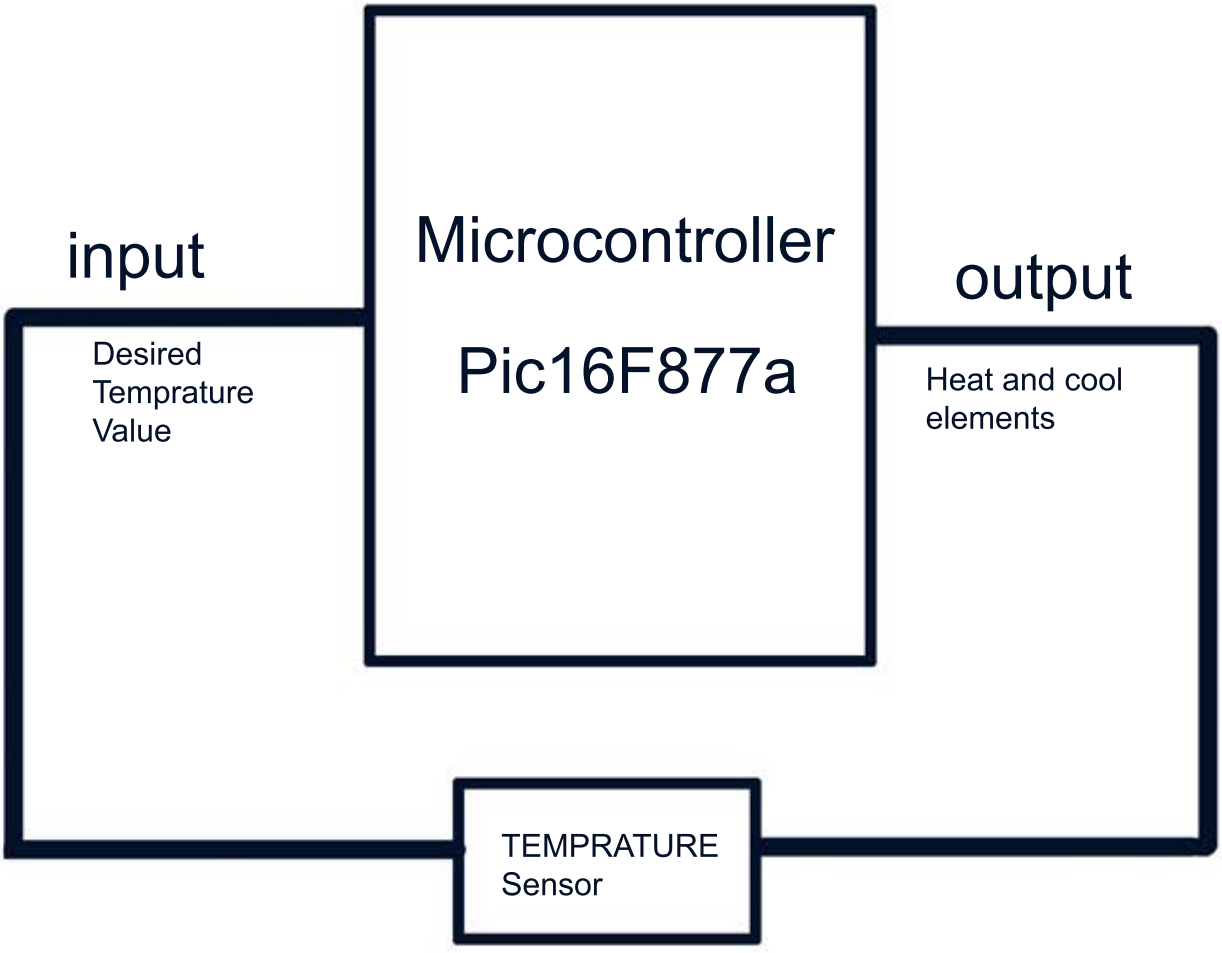
-نادر هانى احمد احمد الحلو

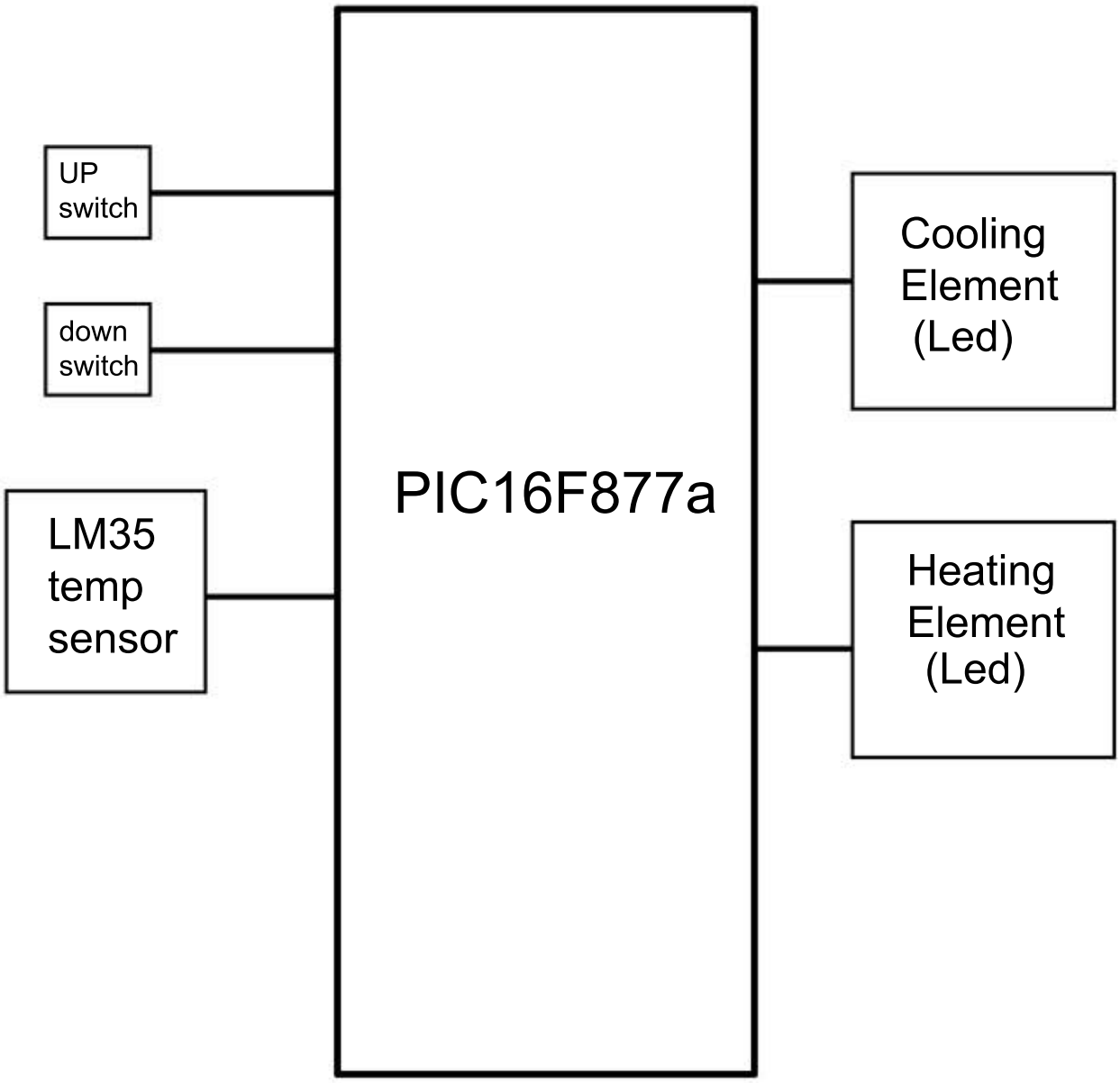
working principle:

the baisic idea of this project is to adjust the tempra ture of the system in which it is embedded with bas ed on the famous microcontroller pic16f877a introd uced from Microchip , as any based computer syst em has an input and output modules .



Components :

1 - PUSH BUTTONS
2 - LM35 Analog temprature sensor
3 - 7segmants + decoder
4 - leds and resistors as (heat and cool elements)



LM35

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TEXAS INSTRUMENTS

SNIS159H – AUGUST 1999 – REVISED DECEMBER 2017

LM35 Precision Centigrade Temperature Sensors

1 Features

- Calibrated Directly in Celsius (Centigrade)
- Linear + 10-mV/°C Scale Factor
- 0.5°C Ensured Accuracy (at 25°C)
- Rated for Full −55°C to 150°C Range
- Suitable for Remote Applications
- Low-Cost Due to Wafer-Level Trimming
- Operates From 4 V to 30 V
- Less Than 60-μA Current Drain
- Low Self-Heating, 0.08°C in Still Air
- Non-Linearity Only ±¼°C Typical
- Low-Impedance Output, 0.1 Ω for 1-mA Load

2 Applications

- Power Supplies
- Battery Management
- HVAC
- Appliances

3 Description

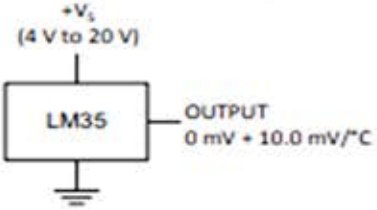
The LM35 series are precision integrated-circuit temperature devices with an output voltage linearly-proportional to the Centigrade temperature. The LM35 device has an advantage over linear temperature sensors calibrated in Kelvin, as the user is not required to subtract a large constant voltage from the output to obtain convenient Centigrade scaling. The LM35 device does not require any external calibration or trimming to provide typical accuracies of ±¼°C at room temperature and ±¾°C over a full −55°C to 150°C temperature range. Lower cost is assured by trimming and calibration at the wafer level. The low-output impedance, linear output, and precise inherent calibration of the LM35 device makes interfacing to readout or control circuitry especially easy. The device is used with single power supplies, or with plus and minus supplies. As the LM35 device draws only 60 μA from the supply, it has very low self-heating of less than 0.1°C in still air. The LM35 device is rated to operate over a −55°C to 150°C temperature range, while the LM35C device is rated for a −40°C to 110°C range (−10° with improved accuracy). The LM35-series devices are available packaged in hermetic TO transistor packages, while the LM35C, LM35CA, and LM35D devices are available in the plastic TO-92 transistor package. The LM35D device is available in an 8-lead surface-mount small-outline package and a plastic TO-220 package.

Device Information[1]

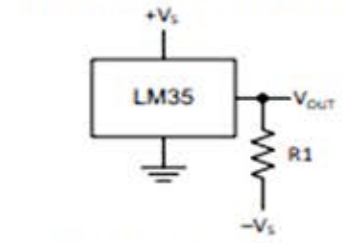
PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM35	TO-CAN (3)	4.699 mm × 4.699 mm
	TO-92 (3)	4.30 mm × 4.30 mm
	SOIC (8)	4.90 mm × 3.91 mm
	TO-220 (3)	14.986 mm × 10.16 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Basic Centigrade Temperature Sensor (2°C to 150°C)



Full-Range Centigrade Temperature Sensor



Choose $R_1 = -V_S / 50\ \mu A$
$V_{OUT} = 1500$ mV at 150°C
$V_{OUT} = 250$ mV at 25°C
$V_{OUT} = -550$ mV at −55°C

LM35

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)(2)

		MIN	MAX	UNIT
Supply voltage		–0.2	35	V
Output voltage		–1	6	V
Output current			10	mA
Maximum Junction Temperature, $T_J$max			150	°C
Storage Temperature, T_{stg}	TO-CAN, TO-92 Package	–60	150	°C
	TO-220, SOIC Package	–65	150	

(1) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2500	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Specified operating temperature: T_{MIN} to T_{MAX}	LM35, LM35A	–55	150	°C
	LM35C, LM35CA	–40	110	
	LM35D	0	100	
Supply Voltage (+V_S)		4	30	V

6.4 Thermal Information

THERMAL METRIC(1)(2)		LM35				UNIT
		NDV	LP	D	NEB	
		3 PINS		8 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	400	180	220	90	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	24	—	—	—	

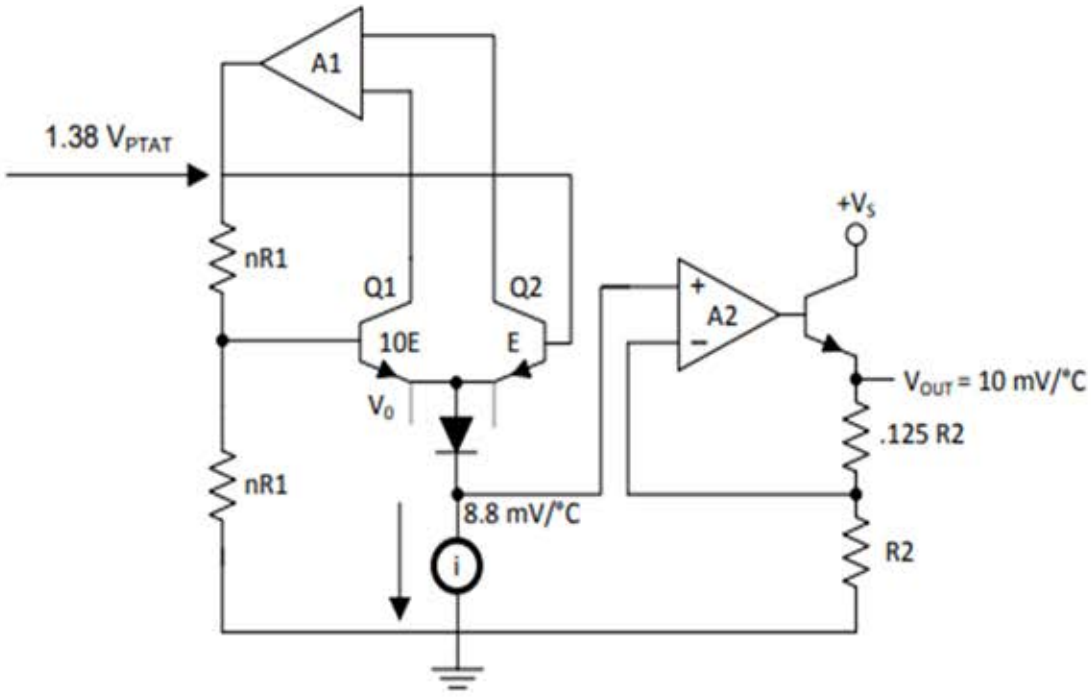
(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.
(2) For additional thermal resistance information, see *Typical Application*.

LM35

The LM35-series devices are precision integrated-circuit temperature sensors, with an output voltage linearly proportional to the Centigrade temperature. The LM35 device has an advantage over linear temperature sensors calibrated in Kelvin, as the user is not required to subtract a large constant voltage from the output to obtain convenient Centigrade scaling. The LM35 device does not require any external calibration or trimming to provide typical accuracies of ± ¼ °C at room temperature and ± ¾ °C over a full −55°C to 150°C temperature range. Lower cost is assured by trimming and calibration at the wafer level. The low output impedance, linear output, and precise inherent calibration of the LM35 device makes interfacing to readout or control circuitry especially easy. The device is used with single power supplies, or with plus and minus supplies. As the LM35 device draws only 60 μA from the supply, it has very low self-heating of less than 0.1°C in still air. The LM35 device is rated to operate over a −55°C to 150°C temperature range, while the LM35C device is rated for a −40°C to 110°C range (−10° with improved accuracy). The temperature-sensing element is comprised of a delta-V BE architecture.

The temperature-sensing element is then buffered by an amplifier and provided to the VOUT pin. The amplifier has a simple class A output stage with typical 0.5-Ω output impedance as shown in the *Functional Block Diagram*. Therefore the LM35 can only source current and it's sinking capability is limited to 1 μA.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 LM35 Transfer Function

The accuracy specifications of the LM35 are given with respect to a simple linear transfer function:

V_{OUT} = 10 mv/°C × T

where

- V_{OUT} is the LM35 output voltage
- T is the temperature in °C

(1)

7.4 Device Functional Modes

The only functional mode of the LM35 is that it has an analog output directly proportional to temperature.

8.3 System Examples

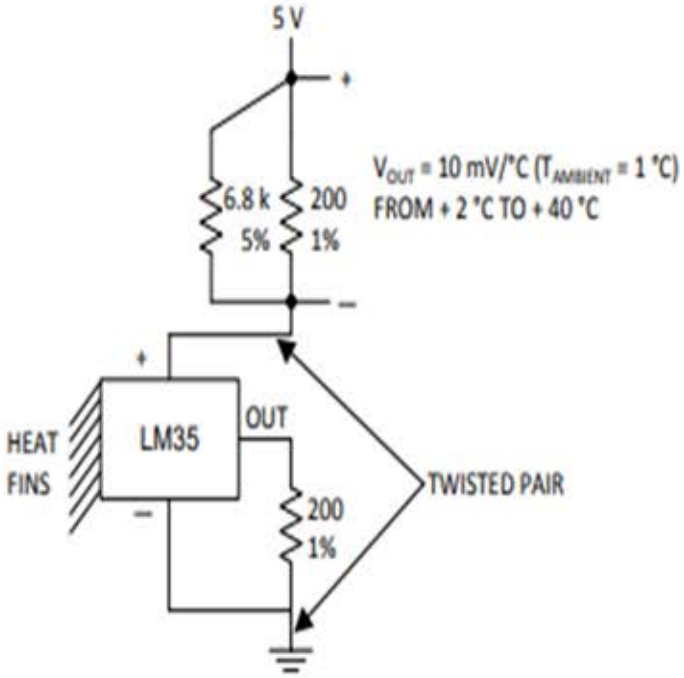


Figure 16. Two-Wire Remote Temperature Sensor (Grounded Sensor)

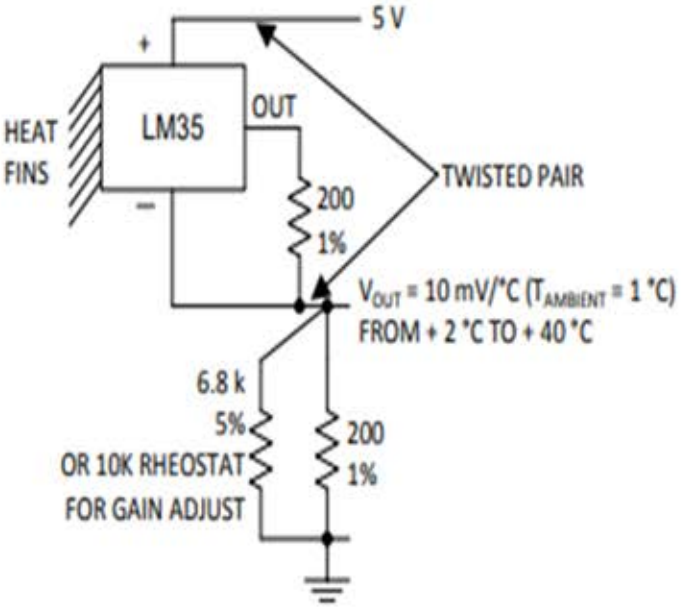


Figure 17. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

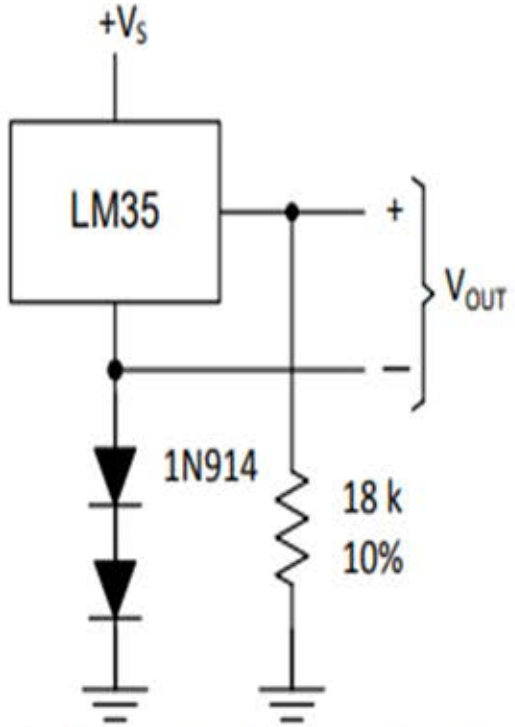


Figure 18. Temperature Sensor, Single Supply (−55° to +150°C)

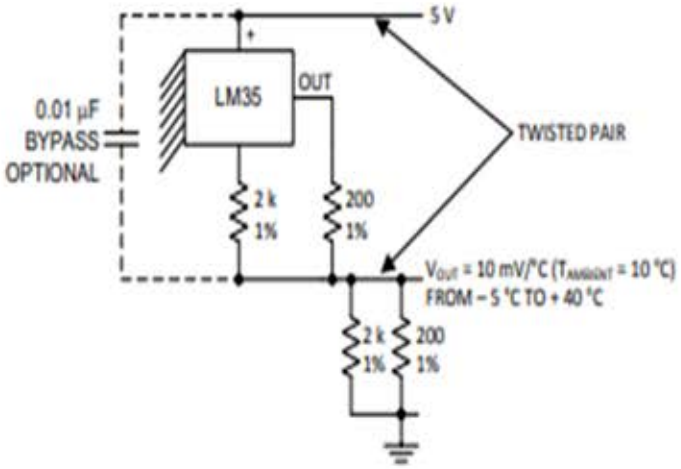


Figure 19. Two-Wire Remote Temperature Sensor (Output Referred to Ground)

7447

FAIRCHILD
SEMICONDUCTOR™

March 1998

DM7446A, DM7447A
BCD to 7-Segment Decoders/Drivers

General Description

The 46A and 47A feature active-low outputs designed for driving common-anode LEDs or incandescent indicators directly. All of the circuits have full ripple-blanking input/output controls and a lamp test input. Segment identification and resultant displays are shown on a following page. Display patterns for BCD input counts above nine are unique symbols to authenticate input conditions.

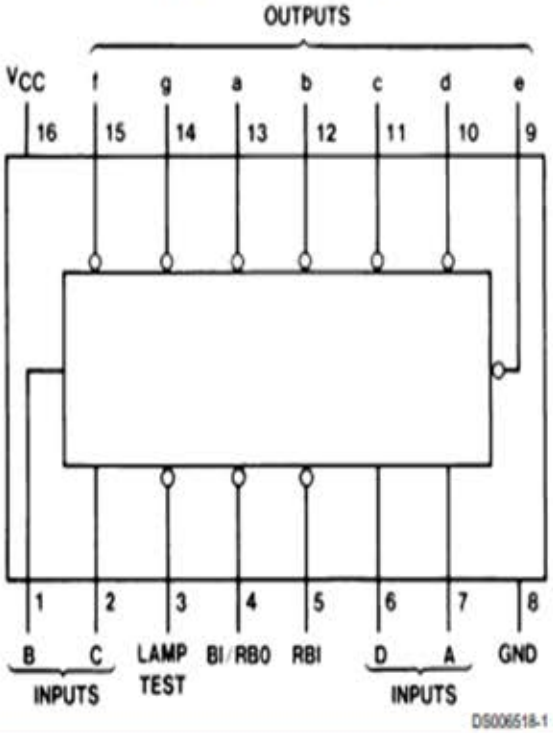
All of the circuits incorporate automatic leading and/or trailing-edge, zero-blanking control (RBI and RBO). Lamp test (LT) of these devices may be performed at any time when the BI/RBO node is at a high logic level. All types contain an overriding blanking input (BI) which can be used to control the lamp intensity (by pulsing) or to inhibit the outputs.

Features

- All circuit types feature lamp intensity modulation capability
- Open-collector outputs drive indicators directly
- Lamp-test provision
- Leading/trailing zero suppression

Connection Diagram

Dual-In-Line Package



DS006518-1

7447

Absolute Maximum Ratings (Note 1)

Supply Voltage	7V
Input Voltage	5.5V
Operating Free Air Temperature Range	
DM54	−55°C to +125°C
DM74	0°C to +70°C
Storage Temperature Range	−65°C to +150°C

Recommended Operating Conditions

Symbol	Parameter	DM7446A			Units
		Min	Nom	Max	
V_{CC}	Supply Voltage	4.75	5	5.25	V
V_{IH}	High Level Input Voltage	2			V
V_{IL}	Low Level Input Voltage			0.8	V
V_{OH}	High Level Output Voltage (a thru g)			30	V
I_{OH}	High Level Output Current (BI/RBO)			−0.2	μA
I_{OL}	Low Level Output Current (a thru g)			40	mA
I_{OL}	Low Level Output Current (BI/RBO)			8	mA
T_A	Free Air Operating Temperature	0		70	°C

Note 1: *The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the "Electrical Characteristics" table are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.*

'46A Electrical Characteristics

over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ (Note 2)	Max	Units
V_I	Input Clamp Voltage	V_{CC} = Min, I_I = −12 mA				−1.5	V
V_{OH}	High Level Output Voltage (BI/RBO)	V_{CC} = Min I_{OH} = Max		2.4	3.7		V
I_{CEX}	High Level Output Current (a thru g)	V_{CC} = Max, V_O = 30V V_{IL} = Max, V_{IH} = Min				250	μA
V_{OL}	Low Level Output Voltage	V_{CC} = Min, I_{OL} = Max V_{IH} = Min, V_{IL} = Max			0.3	0.4	V
I_I	Input Current @ Max Input Voltage	V_{CC} = Max, V_I = 5.5V (Except BI/RBO)				1	mA
I_{IH}	High Level Input Current	V_{CC} = Max, V_I = 2.4V (Except BI/RBO)				40	μA
I_{IL}	Low Level Input Current	V_{CC} = Max V_I = 0.4V	BI/RBO			−4	mA
			Others			−1.6	
I_{OS}	Short Circuit Output Current	V_{CC} = Max (BI/RBO)				−4	mA
I_{CC}	Supply Current	V_{CC} = Max (Note 3)			60	103	mA

Note 2: All typicals are at V_{CC} = 5V, T_A = 25°C.

Note 3: I_{CC} is measured with all outputs open and all inputs at 4.5V.

7447

'47A Switching Characteristics

at V_{CC} = 5V and T_A = 25°C (See Section 1 for Test Waveforms and Output Load)

Symbol	Parameter	Conditions	Min	Max	Units
t_{PLH}	Propagation Delay Time Low to High Level Output	C_L = 15 pF R_L = 120Ω		100	ns
t_{PHL}	Propagation Delay Time High to Low Level Output			100	ns

Function Table

46A, 47A

Decimal or Function	Inputs						BI/RBO (Note 6)	Outputs							Note
	LT	RBI	D	C	B	A		a	b	c	d	e	f	g	
0	H	H	L	L	L	L	H	L	L	L	L	L	L	H	
1	H	X	L	L	L	H	H	H	L	L	H	H	H	H	
2	H	X	L	L	H	L	H	L	L	H	L	L	H	L	
3	H	X	L	L	H	H	H	L	L	L	L	H	H	L	
4	H	X	L	H	L	L	H	H	L	L	H	H	L	L	
5	H	X	L	H	L	H	H	L	H	L	L	H	L	L	
6	H	X	L	H	H	L	H	H	H	L	L	L	L	L	
7	H	X	L	H	H	H	H	L	L	L	H	H	H	H	(Note 7)
8	H	X	H	L	L	L	H	L	L	L	L	L	L	L	
9	H	X	H	L	L	H	H	L	L	L	H	H	L	L	
10	H	X	H	L	H	L	H	H	H	H	L	L	H	L	
11	H	X	H	L	H	H	H	H	H	L	L	H	H	L	
12	H	X	H	H	L	L	H	H	L	H	H	H	L	L	
13	H	X	H	H	L	H	H	L	H	H	L	H	L	L	
14	H	X	H	H	H	L	H	H	H	H	L	L	L	L	
15	H	X	H	H	H	H	H	H	H	H	H	H	H	H	
BI	X	X	X	X	X	X	L	H	H	H	H	H	H	H	(Note 8)
RBI	H	L	L	L	L	L	L	H	H	H	H	H	H	H	(Note 9)
LT	L	X	X	X	X	X	H	L	L	L	L	L	L	L	(Note 10)

H = High level, L = Low level, X = Don't Care

Note 6: BI/RBO is a wire-AND logic serving as blanking input (BI) and/or ripple-blanking output (RBO).

Note 7: The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired. The ripple-blanking input (RBI) must be open or high if blanking of a decimal zero is not desired.

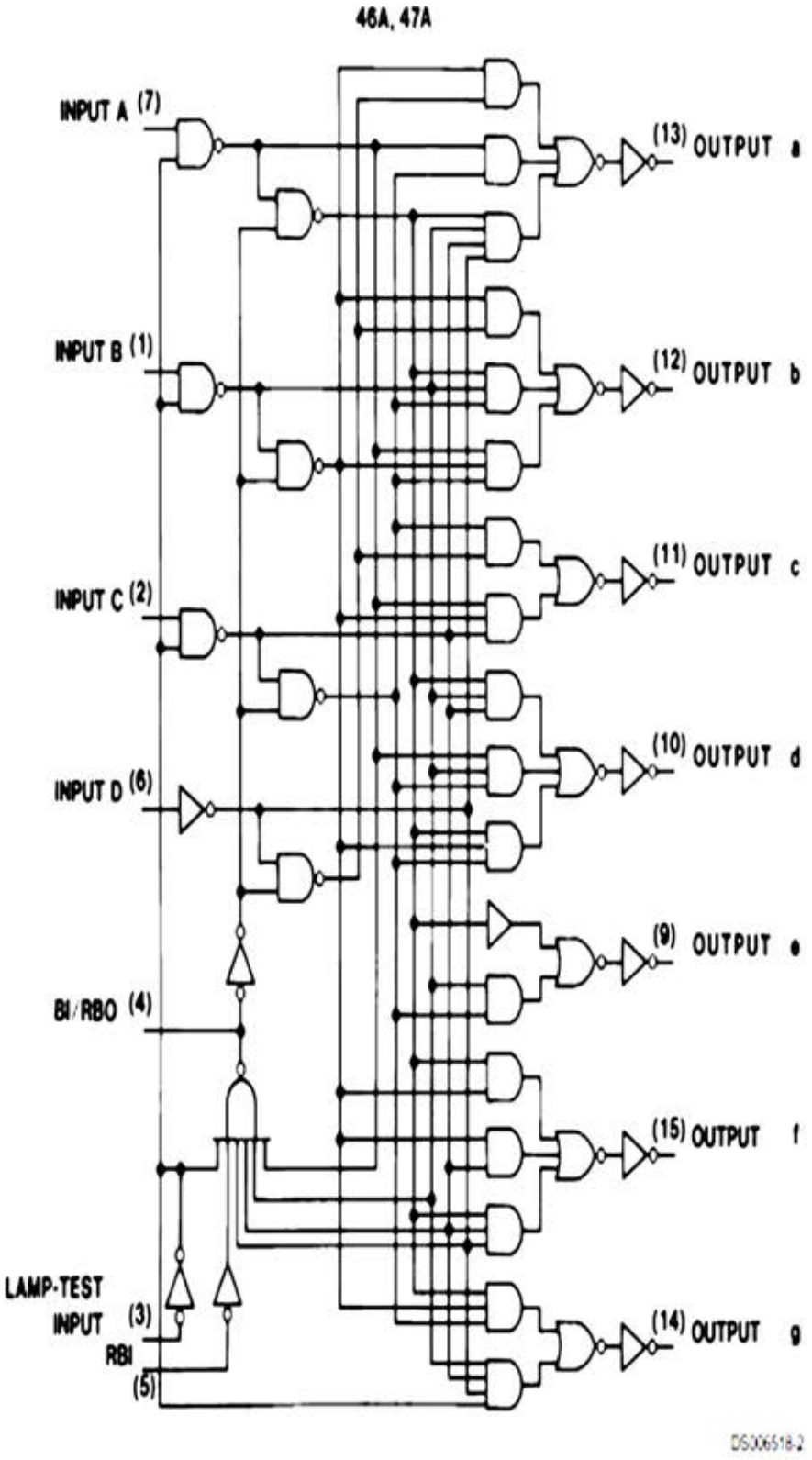
Note 8: When a low logic level is applied directly to the blanking input (BI), all segment outputs are high regardless of the level of any other input.

Note 9: When ripple-blanking input (RBI) and inputs A, B, C, and D are at a low level with the lamp test input high, all segment outputs go H and the ripple-blanking output (RBO) goes to a low level (response condition).

Note 10: When the blanking input/ripple-blanking output (BI/RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are L .

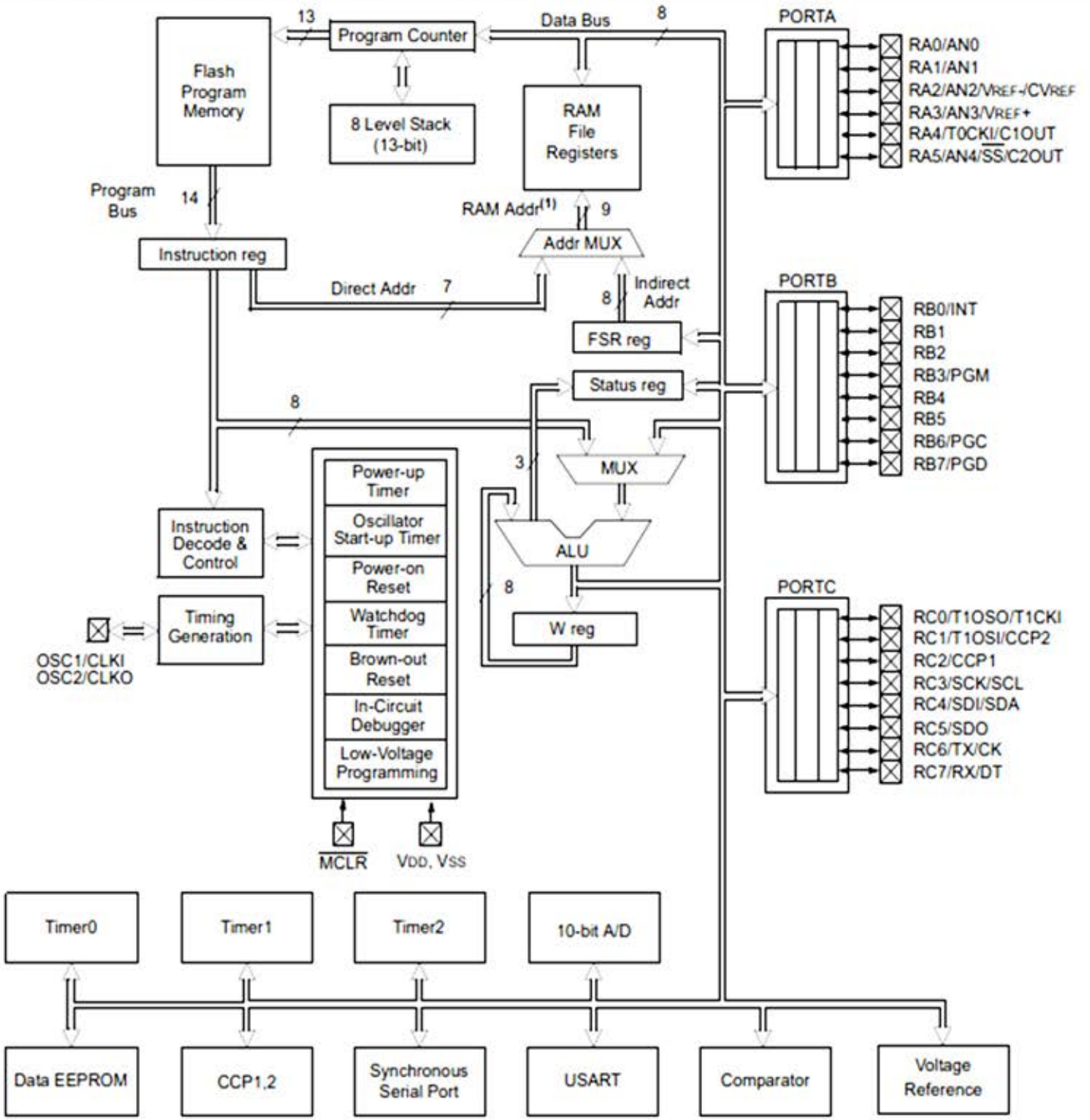
7447

Logic Diagram



pic16F877A

FIGURE 1-1: PIC16F873A/876A BLOCK DIAGRAM



Device	Program Flash	Data Memory	Data EEPROM
PIC16F873A	4K words	192 Bytes	128 Bytes
PIC16F876A	8K words	368 Bytes	256 Bytes

pic16F877A

4.0 I/O PORTS

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Additional information on I/O ports may be found in the PICmicro™ Mid-Range Reference Manual (DS33023).

4.1 PORTA and the TRISA Register

PORTA is a 6-bit wide, bidirectional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., put the contents of the output latch on the selected pin).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, the value is modified and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open-drain output. All other PORTA pins have TTL input levels and full CMOS output drivers.

Other PORTA pins are multiplexed with analog inputs and the analog VREF input for both the A/D converters and the comparators. The operation of each pin is selected by clearing/setting the appropriate control bits in the ADCON1 and/or CMCON registers.

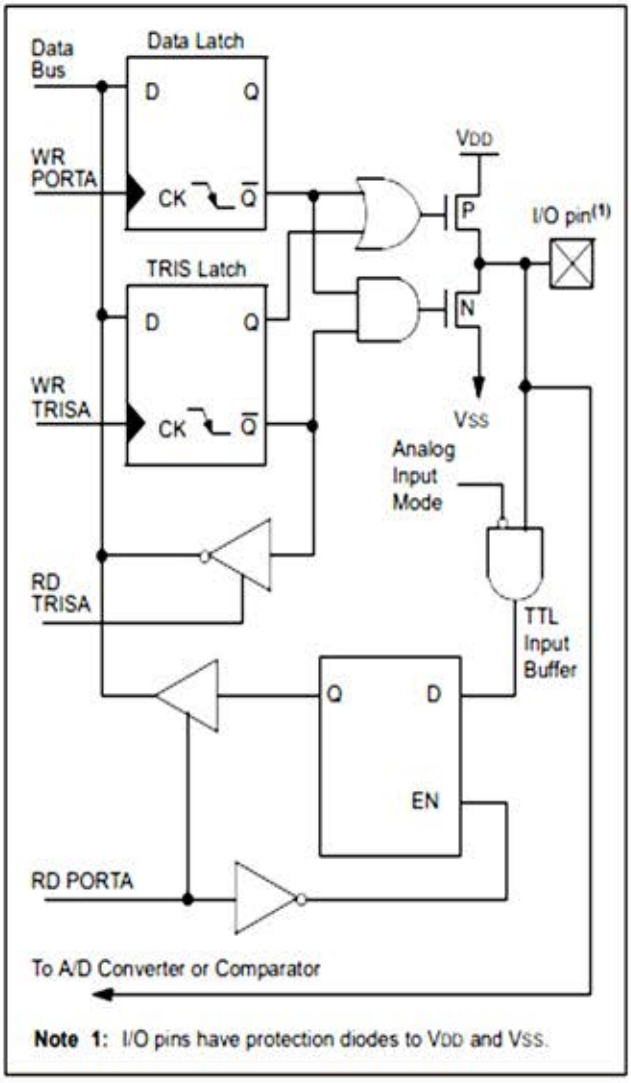
Note:	On a Power-on Reset, these pins are configured as analog inputs and read as '0'. The comparators are in the off (digital) state.

The TRISA register controls the direction of the port pins even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

EXAMPLE 4-1: INITIALIZING PORTA

```
BCF     STATUS, RP0   ;
BCF     STATUS, RP1   ; Bank0
CLRF    PORTA         ; Initialize PORTA by
                      ; clearing output
                      ; data latches
BSF     STATUS, RP0   ; Select Bank 1
MOVLW   0x06          ; Configure all pins
MOVWF   ADCON1        ; as digital inputs
MOVLW   0xCF          ; Value used to
                      ; initialize data
                      ; direction
MOVWF   TRISA         ; Set RA<3:0> as inputs
                      ; RA<5:4> as outputs
                      ; TRISA<7:6>are always
                      ; read as '0'.
```

FIGURE 4-1: BLOCK DIAGRAM OF RA3:RA0 PINS



Note 1: I/O pins have protection diodes to VDD and VSS.

pic16F877A

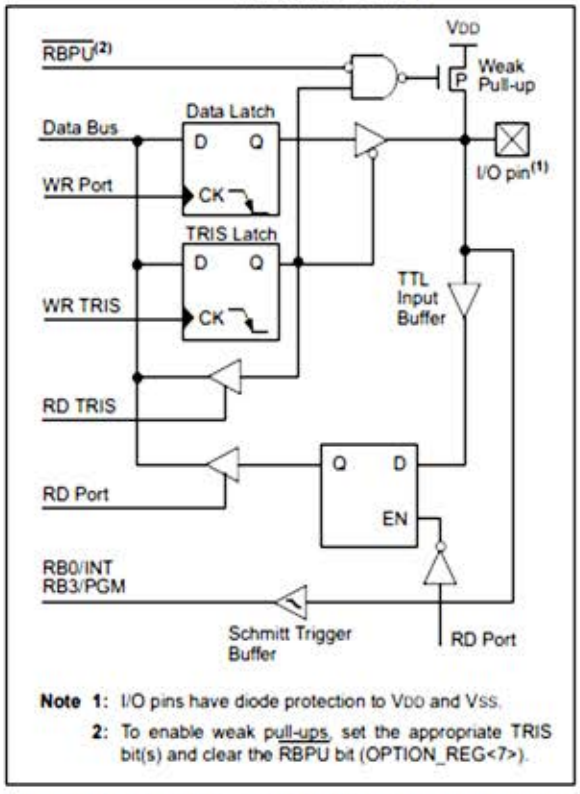
4.2 PORTB and the TRISB Register

PORTB is an 8-bit wide, bidirectional port. The corresponding data direction register is TRISB. Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., put the contents of the output latch on the selected pin).

Three pins of PORTB are multiplexed with the In-Circuit Debugger and Low-Voltage Programming function: RB3/PGM, RB6/PGC and RB7/PGD. The alternate functions of these pins are described in **Section 14.0 "Special Features of the CPU"**.

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (OPTION_REG<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

FIGURE 4-4: BLOCK DIAGRAM OF RB3:RB0 PINS



Note 1: I/O pins have diode protection to VDD and VSS.

2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

Four of the PORTB pins, RB7:RB4, have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB port change interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.
b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

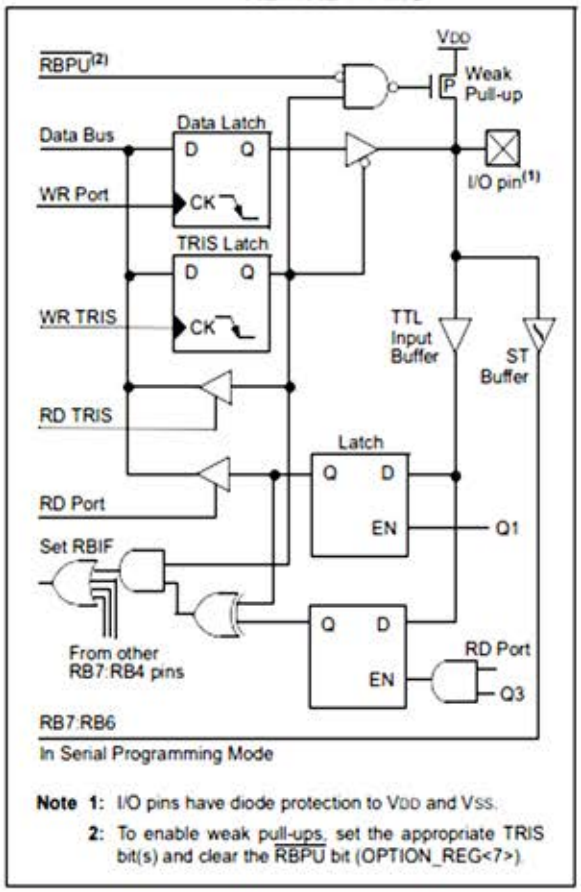
The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

This interrupt-on-mismatch feature, together with software configurable pull-ups on these four pins, allow easy interface to a keypad and make it possible for wake-up on key depression. Refer to the application note, *AN552, "Implementing Wake-up on Key Stroke"* (DS00552).

RB0/INT is an external interrupt input pin and is configured using the INTEDG bit (OPTION_REG<6>).

RB0/INT is discussed in detail in **Section 14.11.1 "INT Interrupt"**.

FIGURE 4-5: BLOCK DIAGRAM OF RB7:RB4 PINS



Note 1: I/O pins have diode protection to VDD and VSS.

2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

pic16F877A

11.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has five inputs for the 28-pin devices and eight for the 40/44-pin devices.

The conversion of an analog input signal results in a corresponding 10-bit digital number. The A/D module has high and low-voltage reference input that is software selectable to some combination of VDD, VSS, RA2 or RA3.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D clock must be derived from the A/D's internal RC oscillator.

The A/D module has four registers. These registers are:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

The ADCON0 register, shown in Register 11-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 11-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be the voltage reference) or as digital I/O.

Additional information on using the A/D module can be found in the PICmicro® Mid-Range MCU Family Reference Manual (DS33023).

REGISTER 11-1: ADCON0 REGISTER (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON
bit 7							bit 0

bit 7-6 **ADCS1:ADCS0:** A/D Conversion Clock Select bits (ADCON0 bits in **bold**)

ADCON1 <ADCS2>	ADCON0 <ADCS1:ADCS0>	Clock Conversion
0	00	Fosc/2
0	01	Fosc/8
0	10	Fosc/32
0	11	FRC (clock derived from the internal A/D RC oscillator)
1	00	Fosc/4
1	01	Fosc/16
1	10	Fosc/64
1	11	FRC (clock derived from the internal A/D RC oscillator)

bit 5-3 **CHS2:CHS0:** Analog Channel Select bits

000 = Channel 0 (AN0)
001 = Channel 1 (AN1)
010 = Channel 2 (AN2)
011 = Channel 3 (AN3)
100 = Channel 4 (AN4)
101 = Channel 5 (AN5)
110 = Channel 6 (AN6)
111 = Channel 7 (AN7)

Note: The PIC16F873A/876A devices only implement A/D channels 0 through 4; the unimplemented selections are reserved. Do not select any unimplemented channels with these devices.

bit 2 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

When ADON = 1:
1 = A/D conversion in progress (setting this bit starts the A/D conversion which is automatically cleared by hardware when the A/D conversion is complete)
0 = A/D conversion not in progress

bit 1 **Unimplemented:** Read as '0'

bit 0 **ADON:** A/D On bit

1 = A/D converter module is powered up
0 = A/D converter module is shut-off and consumes no operating current

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

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REGISTER 11-2: ADCON1 REGISTER (ADDRESS 9Fh)

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	ADCS2	—	—	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified. Six (6) Most Significant bits of ADRESH are read as '0'.
0 = Left justified. Six (6) Least Significant bits of ADRESL are read as '0'.

bit 6 **ADCS2:** A/D Conversion Clock Select bit (ADCON1 bits in shaded area and in **bold**)

ADCON1 <ADCS2>	ADCON0 <ADCS1:ADCS0>	Clock Conversion
0	00	FOSC/2
0	01	FOSC/8
0	10	FOSC/32
0	11	FRC (clock derived from the internal A/D RC oscillator)
1	00	FOSC/4
1	01	FOSC/16
1	10	FOSC/64
1	11	FRC (clock derived from the internal A/D RC oscillator)

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **PCFG3:PCFG0:** A/D Port Configuration Control bits

PCFG <3:0>	AN7	AN6	AN5	AN4	AN3	AN2	AN1	AN0	VREF+	VREF-	C/R
0000	A	A	A	A	A	A	A	A	VDD	VSS	8/0
0001	A	A	A	A	VREF+	A	A	A	AN3	VSS	7/1
0010	D	D	D	A	A	A	A	A	VDD	VSS	5/0
0011	D	D	D	A	VREF+	A	A	A	AN3	VSS	4/1
0100	D	D	D	D	A	D	A	A	VDD	VSS	3/0
0101	D	D	D	D	VREF+	D	A	A	AN3	VSS	2/1
011x	D	D	D	D	D	D	D	D	—	—	0/0
1000	A	A	A	A	VREF+	VREF-	A	A	AN3	AN2	6/2
1001	D	D	A	A	A	A	A	A	VDD	VSS	6/0
1010	D	D	A	A	VREF+	A	A	A	AN3	VSS	5/1
1011	D	D	A	A	VREF+	VREF-	A	A	AN3	AN2	4/2
1100	D	D	D	A	VREF+	VREF-	A	A	AN3	AN2	3/2
1101	D	D	D	D	VREF+	VREF-	A	A	AN3	AN2	2/2
1110	D	D	D	D	D	D	D	A	VDD	VSS	1/0
1111	D	D	D	D	VREF+	VREF-	D	A	AN3	AN2	1/2

A = Analog input D = Digital I/O
C/R = # of analog input channels/# of A/D voltage references

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

Note: On any device Reset, the port pins that are multiplexed with analog functions (ANx) are forced to be an analog input.

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The ADRESH:ADRESL registers contain the 10-bit result of the A/D conversion. When the A/D conversion is complete, the result is loaded into this A/D Result register pair, the GO/$\overline{\text{DONE}}$ bit (ADCON0<2>) is cleared and the A/D interrupt flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 11-1.

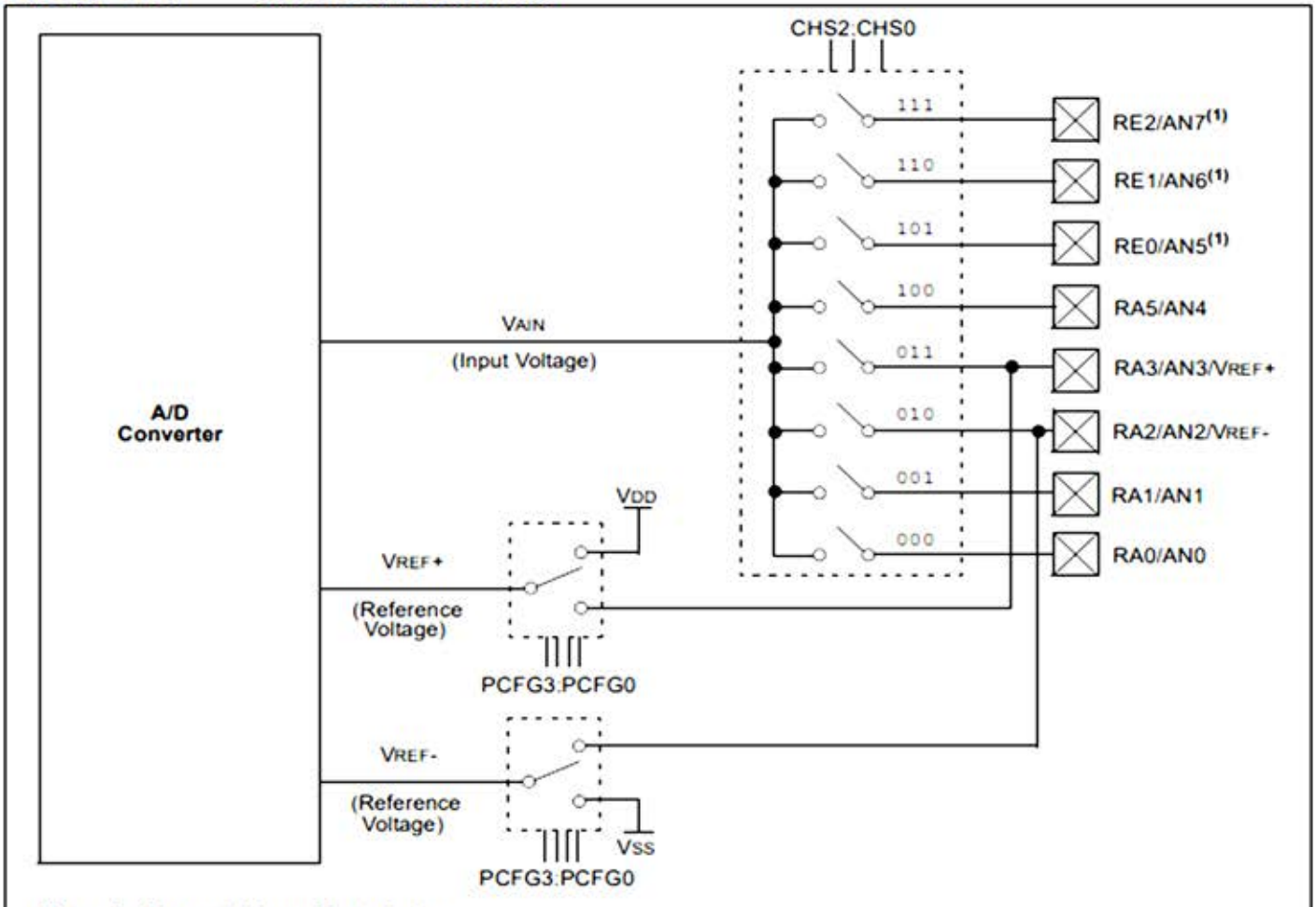
After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs.

To determine sample time, see **Section 11.1 "A/D Acquisition Requirements"**. After this acquisition time has elapsed, the A/D conversion can be started.

To do an A/D Conversion, follow these steps:

1. Configure the A/D module:
   - Configure analog pins/voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D conversion clock (ADCON0)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set PEIE bit
   - Set GIE bit
3. Wait the required acquisition time.
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0)
5. Wait for A/D conversion to complete by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared (interrupts disabled); OR
   - Waiting for the A/D interrupt
6. Read A/D Result register pair (ADRESH:ADRESL), clear bit ADIF if required.
7. For the next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as TAD.

FIGURE 11-1: A/D BLOCK DIAGRAM



Note 1: Not available on 28-pin devices.

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11.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 11-2. The source impedance (RS) and the internal sampling switch impedance (RSS) directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD); see Figure 11-2. **The maximum recommended impedance for analog sources is 2.5 kΩ.** As the impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 11-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

To calculate the minimum acquisition time, TACQ, see the PICmicro® Mid-Range MCU Family Reference Manual (DS33023).

EQUATION 11-1: ACQUISITION TIME

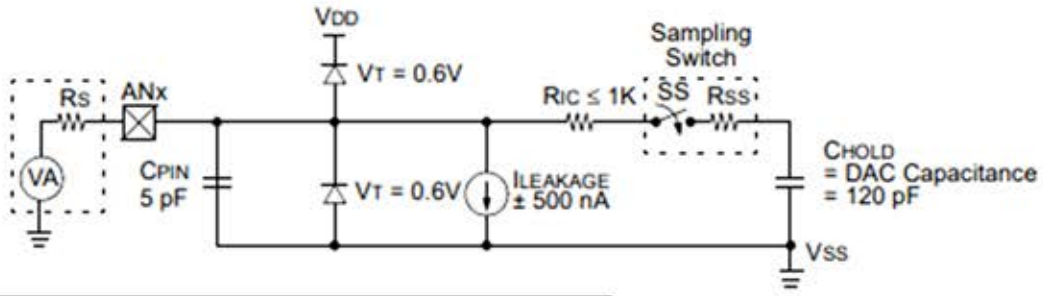
$$
\begin{aligned}
T_{ACQ} &= \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient} \\
&= T_{AMP} + T_C + T_{COFF} \\
&= 2\,\mu s + T_C + [(\text{Temperature} - 25^\circ C)(0.05\,\mu s/^\circ C)] \\
T_C &= C_{HOLD}(R_{IC} + R_{SS} + R_S)\ln(1/2047) \\
&= -120\,pF\,(1\,k\Omega + 7\,k\Omega + 10\,k\Omega)\ln(0.0004885) \\
&= 16.47\,\mu s \\
T_{ACQ} &= 2\,\mu s + 16.47\,\mu s + [(50^\circ C - 25^\circ C)(0.05\,\mu s/^\circ C)] \\
&= 19.72\,\mu s
\end{aligned}
$$

Note 1: The reference voltage (VREF) has no effect on the equation since it cancels itself out.

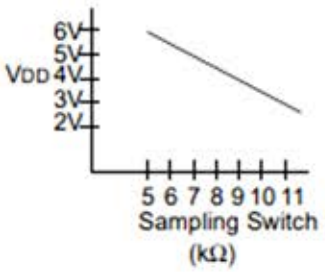
2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 2.5 kΩ. This is required to meet the pin leakage specification.

FIGURE 11-2: ANALOG INPUT MODEL



Legend:
- CPIN = input capacitance
- VT = threshold voltage
- ILEAKAGE = leakage current at the pin due to various junctions
- RIC = interconnect resistance
- SS = sampling switch
- CHOLD = sample/hold capacitance (from DAC)



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11.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires a minimum 12 TAD per 10-bit conversion. The source of the A/D conversion clock is software selected. The seven possible options for TAD are:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal A/D module RC oscillator (2-6 µs)

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 µs.

Table 11-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

11.3 Configuring Analog Port Pins

The ADCON1 and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, any pin configured as an analog input channel will read as cleared (a low level). Pins configured as digital inputs will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

2: Analog levels on any pin that is defined as a digital input (including the AN7:AN0 pins) may cause the input buffer to consume current that is out of the device specifications.

TABLE 11-1: TAD vs. MAXIMUM DEVICE OPERATING FREQUENCIES (STANDARD DEVICES (F))

AD Clock Source (TAD)		Maximum Device Frequency
Operation	ADCS2:ADCS1:ADCS0	
2 TOSC	000	1.25 MHz
4 TOSC	100	2.5 MHz
8 TOSC	001	5 MHz
16 TOSC	101	10 MHz
32 TOSC	010	20 MHz
64 TOSC	110	20 MHz
RC(1, 2, 3)	x11	**(Note 1)**

Note 1: The RC source has a typical TAD time of 4 µs but can vary between 2-6 µs.

2: When the device frequencies are greater than 1 MHz, the RC A/D conversion clock source is only recommended for Sleep operation.

3: For extended voltage devices (LF), please refer to **Section 17.0 "Electrical Characteristics"**.

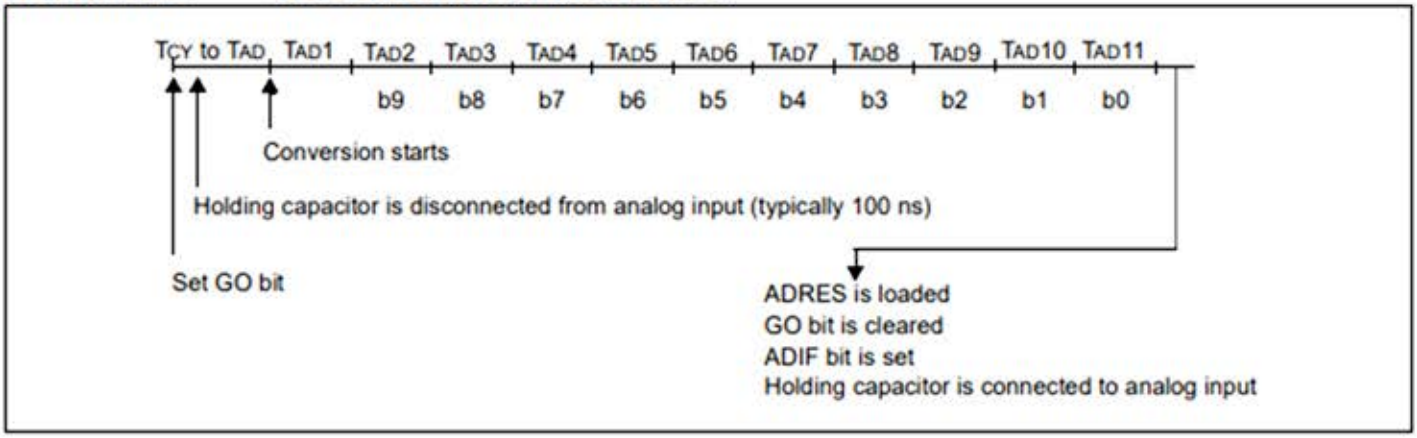
11.4 A/D Conversions

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. That is, the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers). After the A/D conversion is aborted, the next acquisition on the selected channel is automatically started. The GO/$\overline{\text{DONE}}$ bit can then be set to start the conversion.

In Figure 11-3, after the GO bit is set, the first time segment has a minimum of TCY and a maximum of TAD.

Note:	The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D.

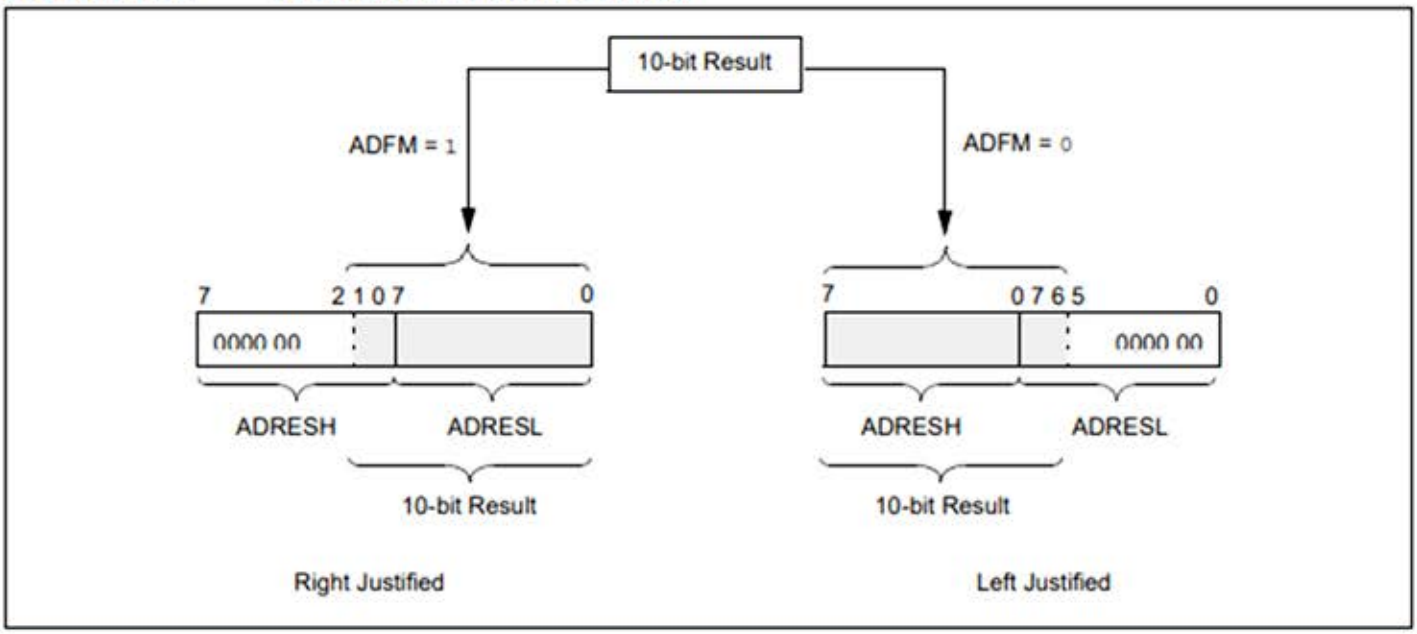
FIGURE 11-3: A/D CONVERSION TAD CYCLES



11.4.1 A/D RESULT REGISTERS

The ADRESH:ADRESL register pair is the location where the 10-bit A/D result is loaded at the completion of the A/D conversion. This register pair is 16 bits wide. The A/D module gives the flexibility to left or right justify the 10-bit result in the 16-bit result register. The A/D Format Select bit (ADFM) controls this justification. Figure 11-4 shows the operation of the A/D result justification. The extra bits are loaded with '0's. When an A/D result will not overwrite these locations (A/D disable), these registers may be used as two general purpose 8-bit registers.

FIGURE 11-4: A/D RESULT JUSTIFICATION



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12.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with I/O port pins RA0 through RA3, while the outputs are multiplexed to pins RA4 and RA5. The on-chip voltage reference (**Section 13.0 "Comparator Voltage Reference Module"**) can also be an input to the comparators.

The CMCON register (Register 12-1) controls the comparator input and output multiplexers. A block diagram of the various comparator configurations is shown in Figure 12-1.

REGISTER 12-1: CMCON REGISTER

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **C2OUT**: Comparator 2 Output bit
When C2INV = 0:
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-
When C2INV = 1:
1 = C2 VIN+ < C2 VIN-
0 = C2 VIN+ > C2 VIN-

bit 6 **C1OUT**: Comparator 1 Output bit
When C1INV = 0:
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-
When C1INV = 1:
1 = C1 VIN+ < C1 VIN-
0 = C1 VIN+ > C1 VIN-

bit 5 **C2INV**: Comparator 2 Output Inversion bit
1 = C2 output inverted
0 = C2 output not inverted

bit 4 **C1INV**: Comparator 1 Output Inversion bit
1 = C1 output inverted
0 = C1 output not inverted

bit 3 **CIS**: Comparator Input Switch bit
When CM2:CM0 = 110:
1 = C1 VIN- connects to RA3/AN3
C2 VIN- connects to RA2/AN2
0 = C1 VIN- connects to RA0/AN0
C2 VIN- connects to RA1/AN1

bit 2 **CM2:CM0**: Comparator Mode bits
Figure 12-1 shows the Comparator modes and CM2:CM0 bit settings.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

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REGISTER 14-1: CONFIGURATION WORD (ADDRESS 2007h)(1)

R/P-1	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1
CP	—	DEBUG	WRT1	WRT0	CPD	LVP	BOREN	—	—	$\overline{\text{PWRTEN}}$	WDTEN	Fosc1	Fosc0
bit 13													bit0

bit 13 **CP:** Flash Program Memory Code Protection bit
1 = Code protection off
0 = All program memory code-protected

bit 12 **Unimplemented:** Read as '1'

bit 11 **DEBUG:** In-Circuit Debugger Mode bit
1 = In-Circuit Debugger disabled, RB6 and RB7 are general purpose I/O pins
0 = In-Circuit Debugger enabled, RB6 and RB7 are dedicated to the debugger

bit 10-9 **WRT1:WRT0** Flash Program Memory Write Enable bits
For PIC16F876A/877A:
11 = Write protection off; all program memory may be written to by EECON control
10 = 0000h to 00FFh write-protected; 0100h to 1FFFh may be written to by EECON control
01 = 0000h to 07FFh write-protected; 0800h to 1FFFh may be written to by EECON control
00 = 0000h to 0FFFh write-protected; 1000h to 1FFFh may be written to by EECON control
For PIC16F873A/874A:
11 = Write protection off; all program memory may be written to by EECON control
10 = 0000h to 00FFh write-protected; 0100h to 0FFFh may be written to by EECON control
01 = 0000h to 03FFh write-protected; 0400h to 0FFFh may be written to by EECON control
00 = 0000h to 07FFh write-protected; 0800h to 0FFFh may be written to by EECON control

bit 8 **CPD:** Data EEPROM Memory Code Protection bit
1 = Data EEPROM code protection off
0 = Data EEPROM code-protected

bit 7 **LVP**: Low-Voltage (Single-Supply) In-Circuit Serial Programming Enable bit
1 = RB3/PGM pin has PGM function; low-voltage programming enabled
0 = RB3 is digital I/O, HV on $\overline{\text{MCLR}}$ must be used for programming

bit 6 **BOREN**: Brown-out Reset Enable bit
1 = BOR enabled
0 = BOR disabled

bit 5-4 **Unimplemented:** Read as '1'

bit 3 **$\overline{\text{PWRTEN}}$**: Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

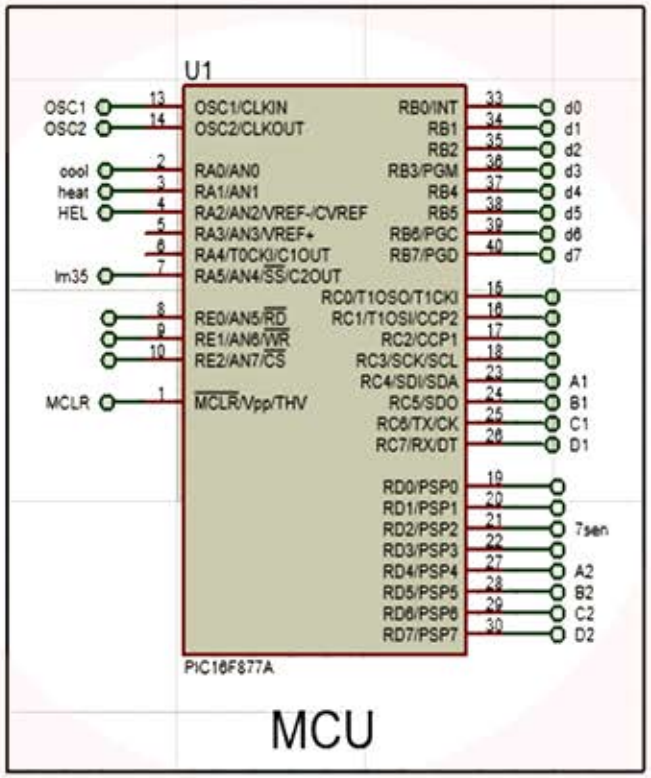
bit 2 **WDTEN**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

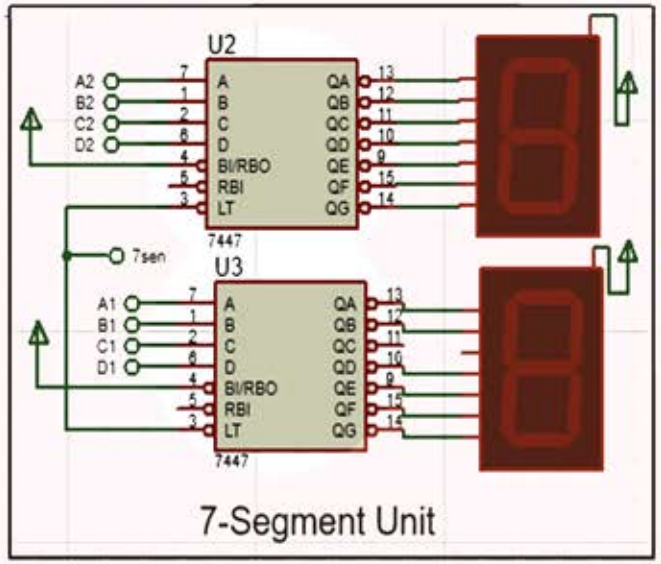
bit 1-0 **Fosc1:Fosc0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

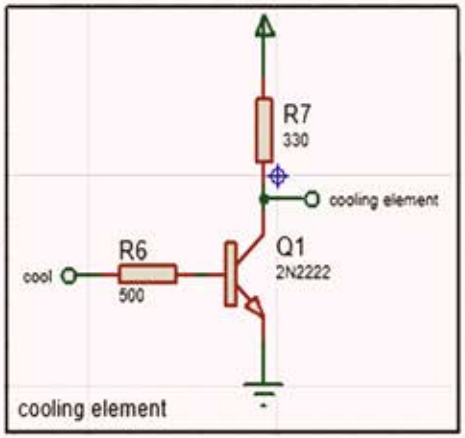
Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed		u = Unchanged from programmed state

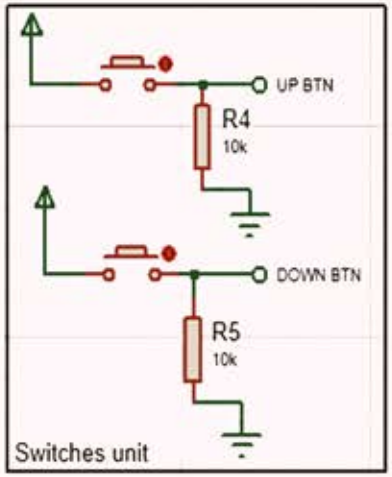
Note 1: The erased (unprogrammed) value of the Configuration Word is 3FFFh.

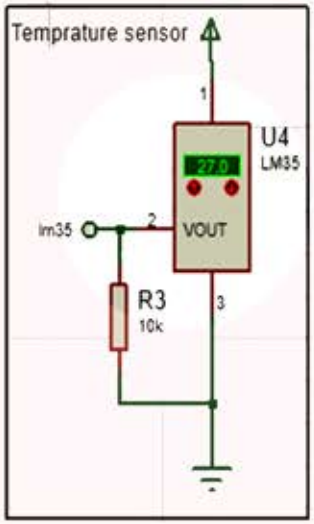
Schematic :

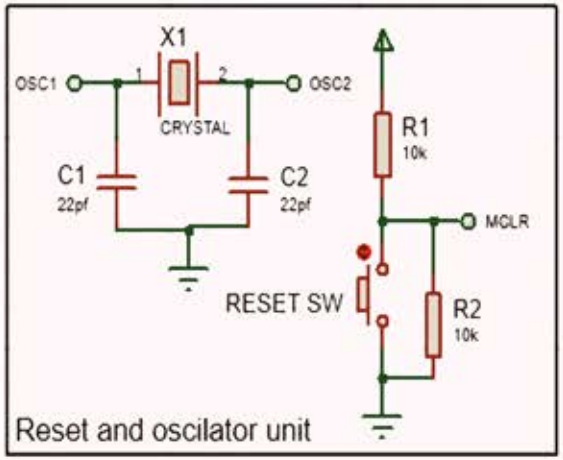

U1
OSC1
OSC2
cool
heat
HEL
lm35
MCLR
OSC1/CLKIN
OSC2/CLKOUT
RA0/AN0
RA1/AN1
RA2/AN2/VREF-/CVREF
RA3/AN3/VREF+
RA4/T0CKI/C1OUT
RA5/AN4/SS/C2OUT
RE0/AN5/RD
RE1/AN6/WR
RE2/AN7/CS
MCLR/Vpp/THV
RB0/INT
RB1
RB2
RB3/PGM
RB4
RB5
RB6/PGC
RB7/PGD
RC0/T1OSO/T1CKI
RC1/T1OSI/CCP2
RC2/CCP1
RC3/SCK/SCL
RC4/SDI/SDA
RC5/SDO
RC6/TX/CK
RC7/RX/DT
RD0/PSP0
RD1/PSP1
RD2/PSP2
RD3/PSP3
RD4/PSP4
RD5/PSP5
RD6/PSP6
RD7/PSP7
d0
d1
d2
d3
d4
d5
d6
d7
A1
B1
C1
D1
7sen
A2
B2
C2
D2
PIC16F877A
MCU

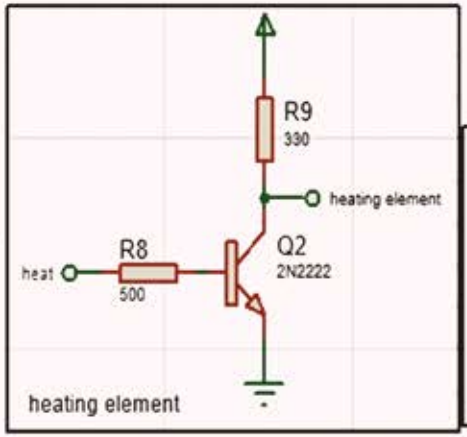

U2
A2
B2
C2
D2
A
B
C
D
BI/RBO
RBI
LT
QA
QB
QC
QD
QE
QF
QG
7447
7sen
U3
A1
B1
C1
D1
7-Segment Unit

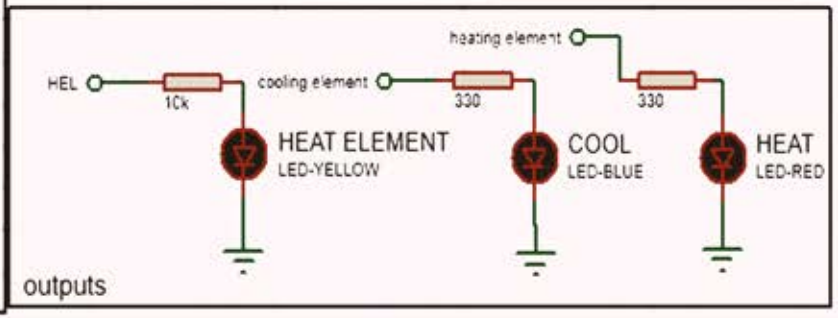

R7
330
cooling element
cool
R6
500
Q1
2N2222
cooling element


UP BTN
R4
10k
DOWN BTN
R5
10k
Switches unit


Temprature sensor
U4
LM35
27.0
lm35
VOUT
R3
10k


X1
OSC1
OSC2
CRYSTAL
C1
22pf
C2
22pf
R1
10k
MCLR
RESET SW
R2
10k
Reset and oscilator unit


R9
330
heating element
heat
R8
500
Q2
2N2222
heating element


heating element
HEL
10k
cooling element
330
330
HEAT ELEMENT
LED-YELLOW
COOL
LED-BLUE
HEAT
LED-RED
outputs